Lam Research Establishes Panel-Level Packaging Center of Excellence in Salzburg, Austria

SALZBURG, Austria, May 20, 2026 — Lam Research Corp. (Nasdaq: LRCX) today announced the establishment of its Panel-Level Packaging Center of Excellence (CoE) in Salzburg, Austria, marking another milestone in the company's ongoing investment in advanced packaging technologies. Lam's new processing lab expands panel-level processing research and development (R&D) and enables closer customer collaboration to evaluate, refine, and scale solutions for evolving packaging needs to meet the demands of the AI era. The Salzburg site builds on the legacy of Semsysco GmbH, founded in Salzburg in 2012 and acquired by Lam Research in 2022. That acquisition added panel-level wet processing expertise and an additional European R&D base to Lam's global laboratory network.

"The expansion of our Salzburg site reflects a long-term investment in advanced packaging," said Aaron Fellis, corporate vice president and general manager, Wet Equipment Technology Systems, Lam Research. "As demand for AI and high-performance technologies continues to grow, the industry must move faster from innovation to manufacturing readiness. Our Panel-Level Packaging CoE strengthens Salzburg's role within Lam's global innovation network and helps increase velocity in R&D through closer collaboration with customers and ecosystem partners."

"Lam Research is a global titan in the semiconductor industry. For Salzburg, the opening of this Panel Center of Excellence is more than an honor; it is a testament to our standing as a high-tech location. This new campus, a state-of-the-art laboratory for panel-level processing, seamlessly bridges the gap from research and development to production," said Karoline Edtstadler, Governor of Salzburg.

Purpose-Built to Increase R&D Velocity as the Industry Shifts from Wafer to Panel

Artificial intelligence, high-performance computing, and heterogeneous integration are driving demand for larger, more complex semiconductor packages. As advanced package designs stretch the limits of round wafers, panel-level processing is being explored across the industry as a path to improved scalability and manufacturing efficiency.

The Salzburg Panel CoE is designed to accelerate the panel-level packaging journey—bringing together panel-focused R&D, infrastructure and engineering talent to help customers move from development toward manufacturing readiness with confidence.

The Salzburg facility is Lam's first panel-focused wet processing R&D site and is fully integrated into the company's global laboratory network. By supporting rapid iteration, early qualification, and customer co-development, the site helps shorten learning cycles and reduce risk as panel-level technologies progress through development and pilot stages. The Salzburg site specializes in panel-level wet-chemical processing for square and rectangular substrates of varying sizes and thicknesses.

This investment demonstrates Lam's commitment to extending its leadership in wet processes for plating, clean, and etch from wafers to panels. Lam's Kallisto™ and Phoenix platforms support electrochemical deposition, etching, and cleaning processes designed with manufacturability, automation, and throughput considerations in mind—helping translate early technical progress into solutions that are scalable in production environments.

Investing in Skills, R&D, and Europe's Semiconductor Innovation Base

Beyond technology development, the Salzburg Panel CoE reflects Lam's continued focus on building capability through people, skills, and research.

"This new lab is an investment in Lam's global lab network strategy," Fellis said. "By expanding advanced packaging R&D in Salzburg, we are strengthening our capabilities to better support customers across Europe and around the world. Connecting specialized local expertise with Lam's global engineering and collaboration network enables faster innovation."

The Salzburg Panel CoE reflects Lam's continued commitment to accelerating innovation—helping customers move faster from concept to manufacturable solutions as panel-level processing becomes increasingly important to the future of semiconductor manufacturing.

About Lam Research

Lam Research Corporation is a global supplier of innovative wafer fabrication equipment and services to the semiconductor industry. Lam's equipment and services allow customers to build smaller and better performing devices. In fact, today, nearly every advanced chip is built with Lam technology. Lam combines systems engineering expertise, technology leadership, and a strong values-based culture, with a commitment to customer collaboration. Lam Research (Nasdaq: LRCX) is a FORTUNE 500® company headquartered in Fremont, California, with operations around the globe. Learn more at www.lamresearch.com.

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